1-1470224-1 ACTIVE

HPI

TE Internal #: 1-1470224-1

PCB Mount Header, Vertical, Wire-to-Board, 11 Position, 2.5 mm [. 098 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder,

Signal, HPI

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Connectors > PCB Connectors > PCB Headers & Receptacles > AMP HPI 2.5 mm Headers



Connector System: Wire-to-Board

Number of Positions: 11

Number of Rows: 1

Centerline (Pitch): 2.5 mm [.098 in]
PCB Mount Orientation: Vertical

All AMP HPI 2.5 mm Headers (78)

Features

Product Type Features

Froduct Type realures	
Connector System	Wire-to-Board
Header Type	Partially Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
PCB Connector Assembly Type	PCB Mount Header
Configuration Features	
Number of Positions	11
Number of Rows	1
PCB Mount Orientation	Vertical
Electrical Characteristics	
Operating Voltage	250 VAC
Body Features	
Primary Product Color	lvory
Contact Features	
Contact Mating Area Length	3.5 mm
	50 μin



Contact Layout	Inline
Mating Pin Diameter	.7 mm[.027 in]
Contact Mating Area Plating Material Thickness	1.27 μm[50 μin]
PCB Contact Termination Area Plating Material Finish	Bright
Contact Mating Area Plating Material Finish	Bright
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Brass
Contact Mating Area Plating Material	Tin
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Terminations per Post (Max)	3
Round Termination Post & Tail Diameter	.7 mm[.027 in]
	.14 in
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Alignment Type	Polarization
Mating Alignment Type Mating Retention	Polarization Without
Mating Retention	Without
Mating Retention Connector Mounting Type	Without Board Mount
Mating Retention Connector Mounting Type Mating Alignment	Without Board Mount With
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment	Without Board Mount With With
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention	Without Board Mount With With
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features	Without Board Mount With Without Without
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features Housing Material	Without Board Mount With Without Without Nylon 66 GF
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch)	Without Board Mount With Without Without Nylon 66 GF
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Dimensions	Without With Without Without Without Nylon 66 GF 2.5 mm[.098 in]
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Dimensions PCB Thickness (Recommended)	Without With Without Without Without Nylon 66 GF 2.5 mm[.098 in]
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Dimensions PCB Thickness (Recommended) Usage Conditions	Without With Without Without Nylon 66 GF 2.5 mm[.098 in] 1.6 mm[.063 in]
Mating Retention Connector Mounting Type Mating Alignment PCB Mount Alignment PCB Mount Retention Housing Features Housing Material Centerline (Pitch) Dimensions PCB Thickness (Recommended) Usage Conditions Operating Temperature Range	Without With Without Without Nylon 66 GF 2.5 mm[.098 in] 1.6 mm[.063 in]



UL Flammability Rating	UL 94V-2
Packaging Features	
Packaging Quantity	250
Packaging Type	Bag, Box

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Yet Reviewed
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: OCT 2008 (15) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 240°C

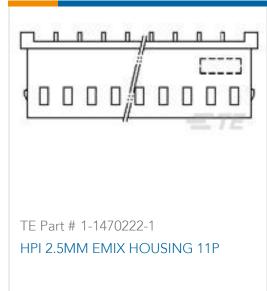
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

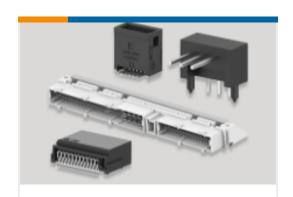
Compatible Parts







Also in the Series | HPI





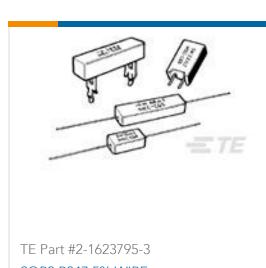


Wire-to-Board Connector Assemblies & Housings(139)



Wire-to-Board Connector Contacts(2)

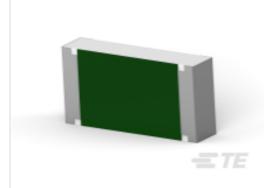
Customers Also Bought







TE Part #1-1630019-4 HSC200 2K4 5%



TE Part #9-2176397-4 3502 7K5 1%



TE Part #1-1969694-4 PTL 1X4 PCB HEADER R/A HITEMP KEY A LGR



TE Part #YD369-B99-AP400000 Rectangular Connectors: 9-Way Panel Mount, 90PCB



TE Part #YDTS24T15-18PNV001 **RECP ASSY**



TE Part #YDTS24T21-35SNV001 **RECP ASSY**

Documents

Product Drawings HPI 2.5MM EMIX A'SSY V/T 11P

English

CAD Files

3D PDF

3D



Customer View Model

ENG_CVM_CVM_1-1470224-1_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-1470224-1_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-1470224-1_E.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Datasheets & Catalog Pages

HPI Connectors QRG

English

Product Specifications

AMP 2.5mm PITCH EMIX WTB SYSTEM.

English

Application Specification

English

Agency Approvals

UL Report

English